PRODUCT ADVANTAGE

High Reliability
100% Reworkable
Enhances Solder Joint Strength 5-10X
Eliminate Underfill
Improve Process Yield
Eliminate Dendrite Formation
Reduce Cost

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OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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The YINCAE® Solder Joint Encapsulant Series is a family of microchip assembly and ball attachment adhesive products that are used to enhance solder joint reliability and eliminate solder joint cracking in CSP, BGA, flip chips and POP microchip applications.

Featured Products

BP 256: Lead free (SAC) ball bumping adhesives

SMT 256: Series of high temperature solder joint encapsulants available in different colors, storage conditions, and filler loads for dip, disperse, and print applications.

SMT 256EP: Combination of solder joint encapsulant and solder paste

SMT 266: Offers a lower viscosity for use in spray, jet, thermal compression bonding, and rework applications.

SMT 138: Series of SnBi based low temperature solder pastes available for dispense, print, and thermal compression bonding applications.

Application of Solder Joint Encapsulant

Microchip Assembling

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.